

Solder Spheres for BGAs

Product Highlights

Chip Quik® BGA solder spheres are manufactured from virgin materials to meet or exceed the requirements of building or repairing BGA packages. Chip Quik® BGA solder spheres also exceed both the IPC and MIL standards for purity levels and size tolerances. Nominal sizes are available from 12 to 30 mil.

Product Specifications

Part Number	Alloy	Melting Point	Diameter	Quantity (by weight)
SMD2165	Sn63/Pb37	183°C (361°F)	0.012" (0.3048mm)	250,000
SMD2165-25000	Sn63/Pb37	183°C (361°F)	0.012" (0.3048mm)	25,000
SMD2180	Sn63/Pb37	183°C (361°F)	0.016" (0.4064mm)	250,000
SMD2180-25000	Sn63/Pb37	183°C (361°F)	0.016" (0.4064mm)	25,000
SMD2190	Sn63/Pb37	183°C (361°F)	0.020" (0.5080mm)	250,000
SMD2190-25000	Sn63/Pb37	183°C (361°F)	0.020" (0.5080mm)	25,000
SMD2200	Sn63/Pb37	183°C (361°F)	0.024" (0.6096mm)	250,000
SMD2200-25000	Sn63/Pb37	183°C (361°F)	0.024" (0.6096mm)	25,000
SMD2205	Sn63/Pb37	183°C (361°F)	0.025" (0.6350mm)	250,000
SMD2205-25000	Sn63/Pb37	183°C (361°F)	0.025" (0.6350mm)	25,000
SMD2215	Sn63/Pb37	183°C (361°F)	0.030" (0.7620mm)	250,000
SMD2215-25000	Sn63/Pb37	183°C (361°F)	0.030" (0.7620mm)	25,000
SMD2040	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.020" (0.5080mm)	250,000
SMD2040-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.020" (0.5080mm)	25,000
SMD2050	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.024" (0.6096mm)	250,000
SMD2050-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.024" (0.6096mm)	25,000
SMD2055	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.025" (0.6350mm)	250,000
SMD2055-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.025" (0.6350mm)	25,000
SMD2060	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.030" (0.7620mm)	250,000
SMD2060-25000	Sn96.5/Ag3.0/Cu0.5	217-220°C (423-428°F)	0.030" (0.7620mm)	25,000

Shelf Life: >24 months

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):
RoHS 2 Directive 2011/65/EU:

Yes
Yes (Sn96.5/Ag3.0/Cu0.5) /
No (Sn63/Pb37)